

# 4V Drive Nch + Nch MOSFET

## **MP6K14**

#### Structure

Silicon N-channel MOSFET

#### Features

- 1) Low on-resistance.
- 2) High power package(MPT6).
- 3) Low voltage drive(4V drive).

# Application

Switching

#### Packaging specifications

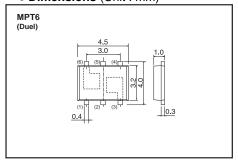
Type	Package	Taping
	Code	TCR
	Basic ordering unit (pieces)	1000
MP6K14		0

#### ● Absolute maximum ratings (Ta = 25°C)

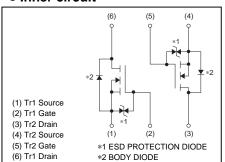
Parameter		Symbol	Limits	Unit
Drain-source voltage		$V_{DSS}$	30	V
Gate-source voltage		$V_{GSS}$	±20	V
Drain current	Continuous	$I_D$	±8.0	Α
	Pulsed	I <sub>DP</sub> *1	±18	А
Source current (Body Diode)	Continuous	l <sub>s</sub>	1.6	Α
	Pulsed	I <sub>sp</sub> *1	18	Α
Power dissipation		P <sub>D</sub> *2	2.0	W / TOTAL
		' D	1.4	W / ELEMENT
Channel temperature		Tch	150	°C
Range of storage temperature		Tstg	-55 to +150	°C

<sup>\*1</sup> Pw≤10µs, Duty cycle≤1%

#### ● Dimensions (Unit : mm)



#### • Inner circuit



<sup>\*2</sup> Mounted on a ceramic board.

# ● Electrical characteristics (Ta = 25°C)

<It is the same ratings for Tr1 and Tr2.>

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gatesource leakage	I <sub>GSS</sub>	-	_	±10	μA	$V_{GS}=\pm20V, V_{DS}=0V$
Drainsource breakdown voltage	V <sub>(BR)DSS</sub>	30	-	_	V	I <sub>D</sub> =1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	-	_	1	μA	$V_{DS}$ =30V, $V_{GS}$ =0V
Gate threshold voltage	V <sub>GS (th)</sub>	1.0	-	2.5	٧	$V_{DS}=10V$ , $I_{D}=1mA$
Otatia duain accura accetata	*	-	18	25	mΩ	I <sub>D</sub> =8.0A, V <sub>GS</sub> =10V
Static drainsource onstate resistance	R <sub>DS (on)</sub>	-	21	29		I <sub>D</sub> =8.0A, V <sub>GS</sub> =4.5V
		-	23	32		I <sub>D</sub> =8.0A, V <sub>GS</sub> =4.0V
Forward transfer admittance	I Y <sub>fs</sub> I*	4.5	_	_	S	I <sub>D</sub> =8.0A, V <sub>DS</sub> =10V
Input capacitance	C <sub>iss</sub>	-	470	_	pF	V <sub>DS</sub> =10V
Output capacitance	C <sub>oss</sub>	-	170	_	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	-	80	_	pF	f=1MHz
Turnon delay time	t <sub>d(on)</sub> *	-	8	_	ns	I <sub>D</sub> =4.0A, V <sub>DD</sub> ≒ 15V
Rise time	t <sub>r</sub> *	-	30	_	ns	V <sub>GS</sub> =10V
Turnoff delay time	t <sub>d(off)</sub> *	-	39	_	ns	$R_L=3.75\Omega$
Fall time	t <sub>f</sub> *	-	9	_	ns	$R_G=10\Omega$
Total gate charge	Q <sub>g</sub> *	_	7.3		nC	I <sub>D</sub> =8.0A, V <sub>DD</sub> ≒15V
Gatesource charge	Q <sub>gs</sub> *	-	1.5	_	nC	V <sub>GS</sub> =5V
Gatedrain charge	Q <sub>gd</sub> *	_	2.9	_	nC	

<sup>\*</sup>Pulsed

## ●Body diode characteristics (Source-Drain) (Ta = 25°C)

<It is the same ratings for Tr1 and Tr2.>

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward Voltage	V <sub>SD</sub> *	_	_	1.2	V	Is=8.0A, V <sub>GS</sub> =0V

<sup>\*</sup>Pulsed

#### ●Electrical characteristic curves (Ta=25°C)

Fig.1 Typical Output Characteristics ( I )

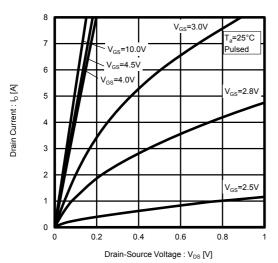


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

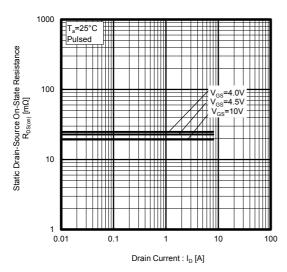


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

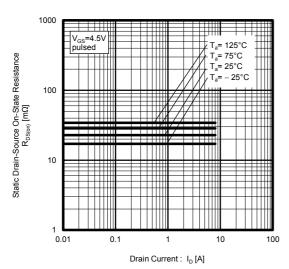


Fig.2 Typical Output Characteristics ( II )

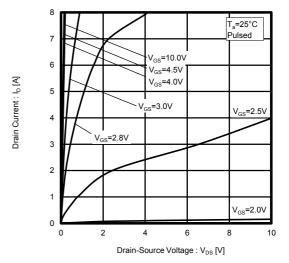


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

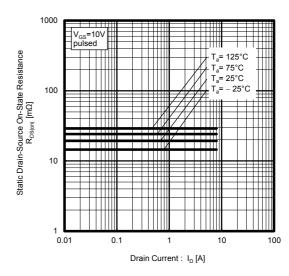
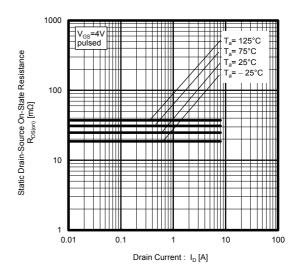


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current





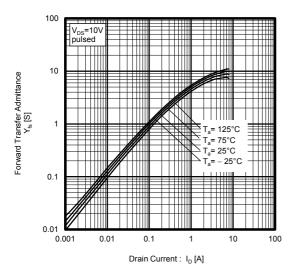


Fig.9 Source Current vs. Source-Drain Voltage

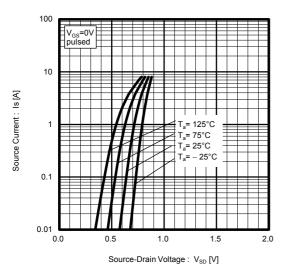


Fig.11 Switching Characteristics

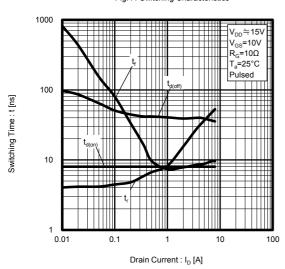


Fig.8 Typical Transfer Characteristics

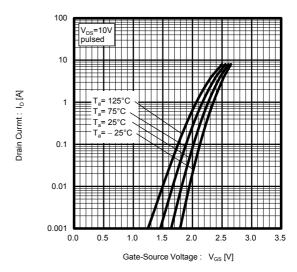


Fig.10 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

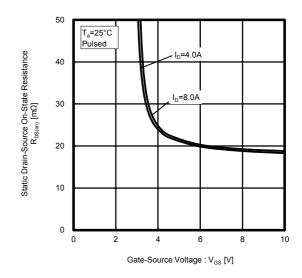


Fig.12 Dynamic Input Characteristics

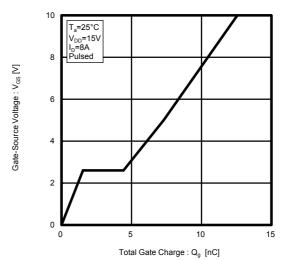


Fig.13 Typical Capacitance vs. Drain-Source Voltage

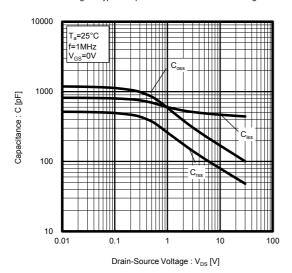


Fig.15 Normalized Transient Thermal Resistance v.s. Pulse Width

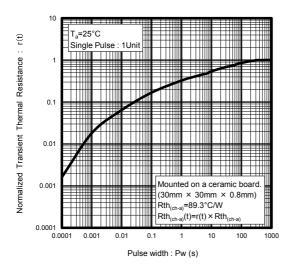
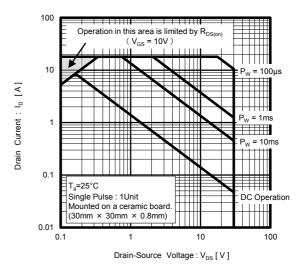


Fig.14 Maximum Safe Operating Area



#### Measurement circuits

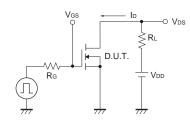


Fig.1-1 Switching Time Measurement Circuit

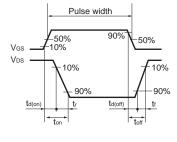


Fig.1-2 Switching Waveforms

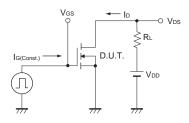


Fig.2-1 Gate Charge Measurement Circuit

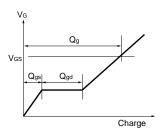


Fig.2-2 Gate Charge Waveform

#### Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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